

Looking below the surface using Ion Beam and DualBeam Techniques

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Micro Advertising



Micro labeling

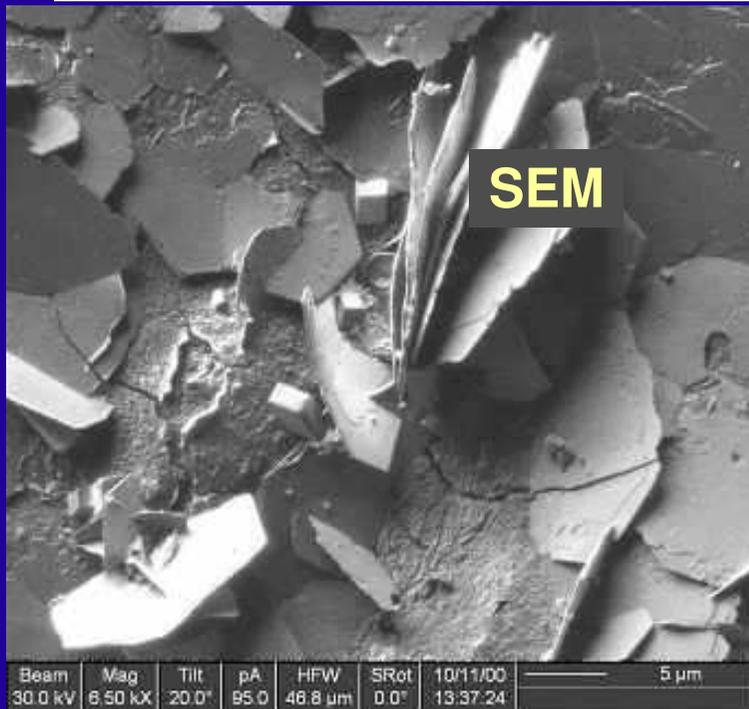
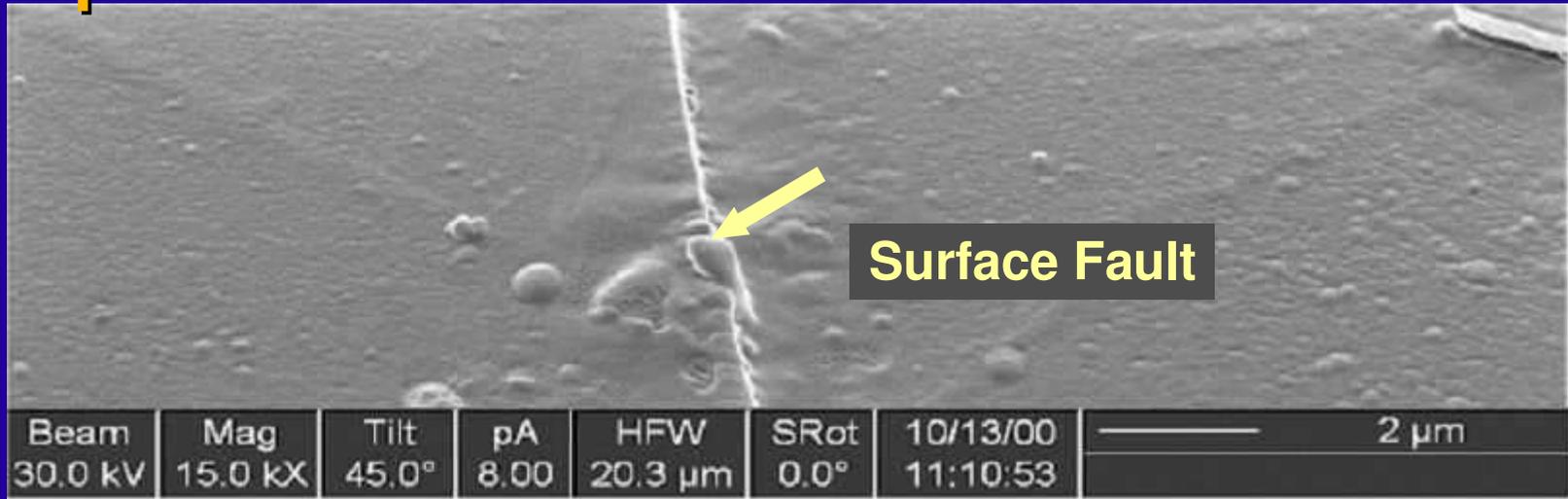
Presentation overview

- Looking below the surface – why?
- Focused Ion Beam main use
- Benefits of an SEM column on the FIB
- Application examples

Why look below surface?

- 3D high resolution materials characterization
- Sub-surface Failure Analysis – Quality Control (incl. Critical Dimensions)
- To bridge the gap between surface microscopy (SEM) to higher resolution sectional microscopy ((S)TEM)

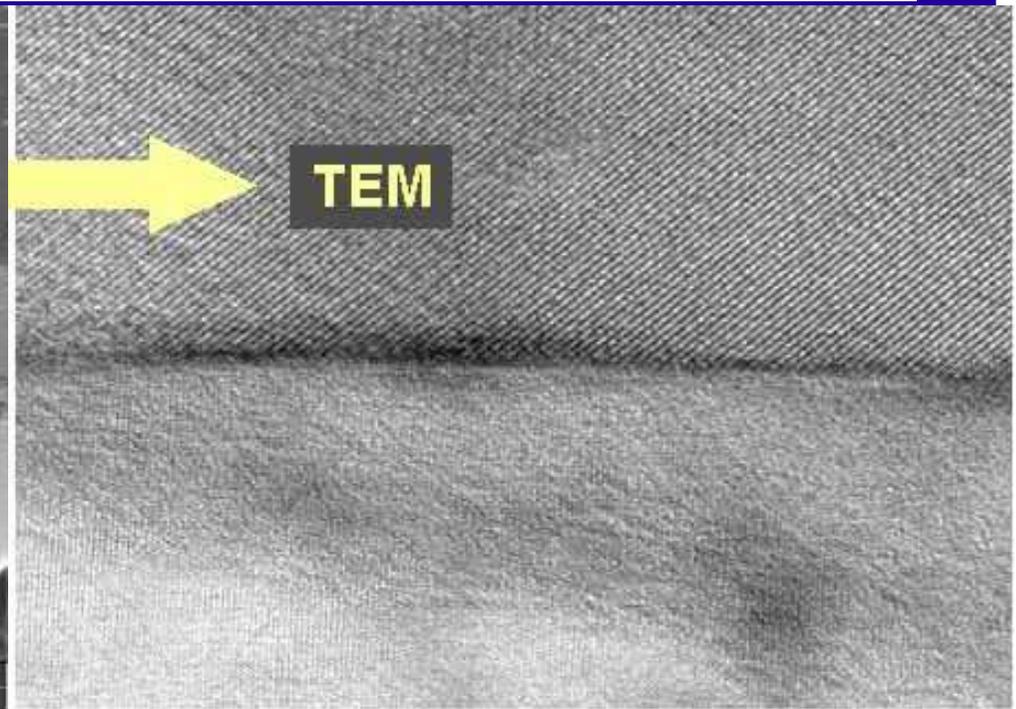
Examples



SEM



TEM



Presentation overview

- Looking below the surface – why?
- **Focused Ion Beam**
- Benefits of an SEM column on the FIB
- Application examples

Focused Ion Beam – Main use

- Removal of material:
 - » Expose 3rd dimension: cross sectioning, slice & view
 - » Foil preparation for STEM and TEM
 - » Circuit edit, nano machining, creation of structures
- Deposition:
 - » Circuit edit, nano fabrication such as proto typing, creation of connects to CNT
- Contrast mechanism: ion channeling (grain contrast)
- SE imaging

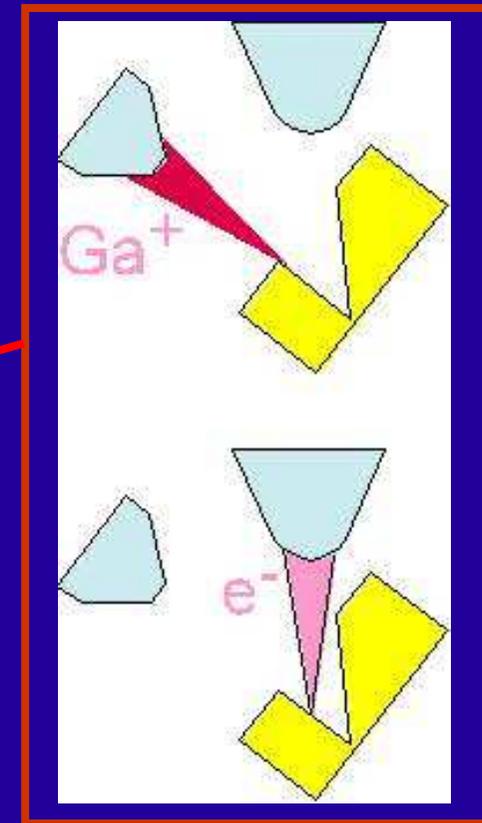
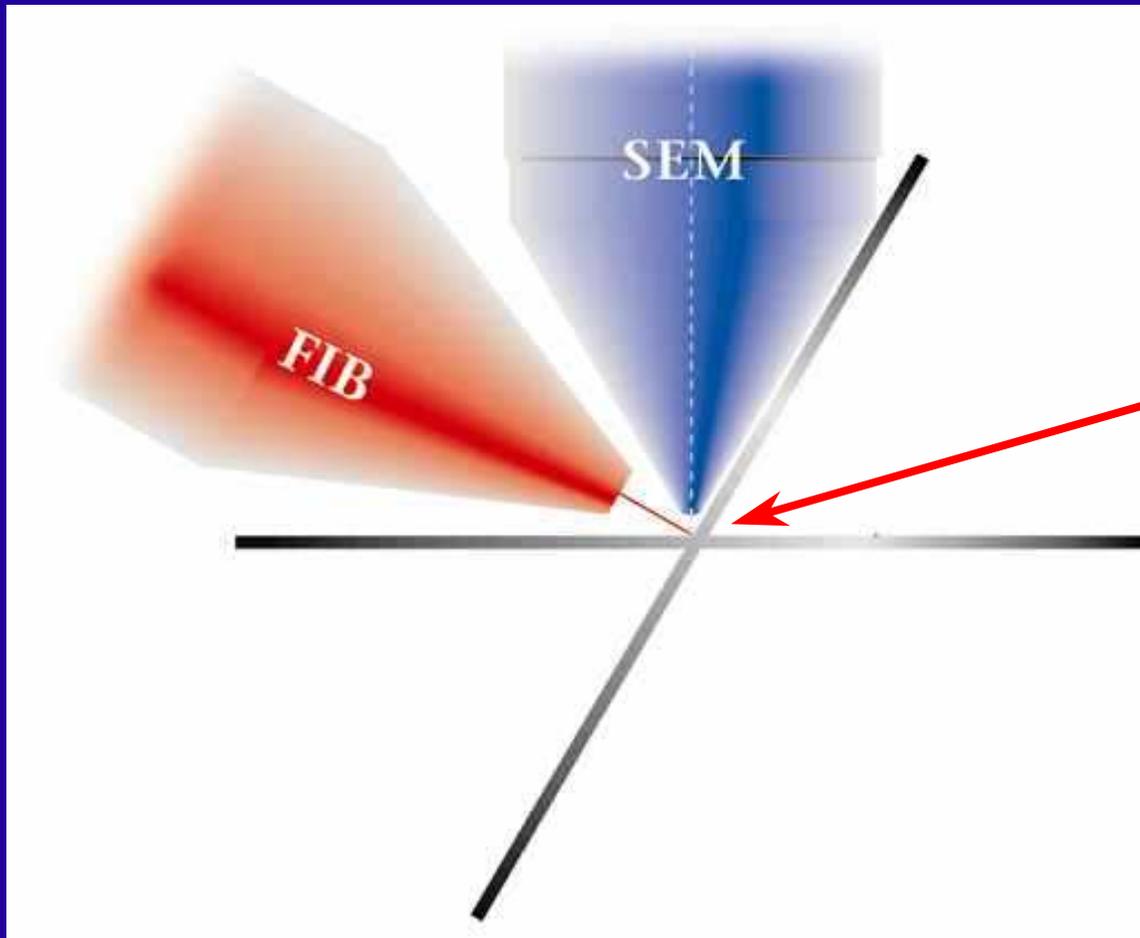
Presentation overview

- Looking below the surface – why?
- Introduction to Focused Ion Beam
- **Benefits of an SEM column on the FIB**
- Application examples

SEM + FIB = DualBeam benefits

- All that of an UHR FEG-SEM
 - » Non-destructive imaging & microanalysis, bulk sample or foil (STEM)
- All that of a FIB
 - » Milling, deposition, channeling contrast
- UHR end-point detection of milling
 - » Monitor the progress and accuracy of milling with an UHR e-beam

DualBeam geometry



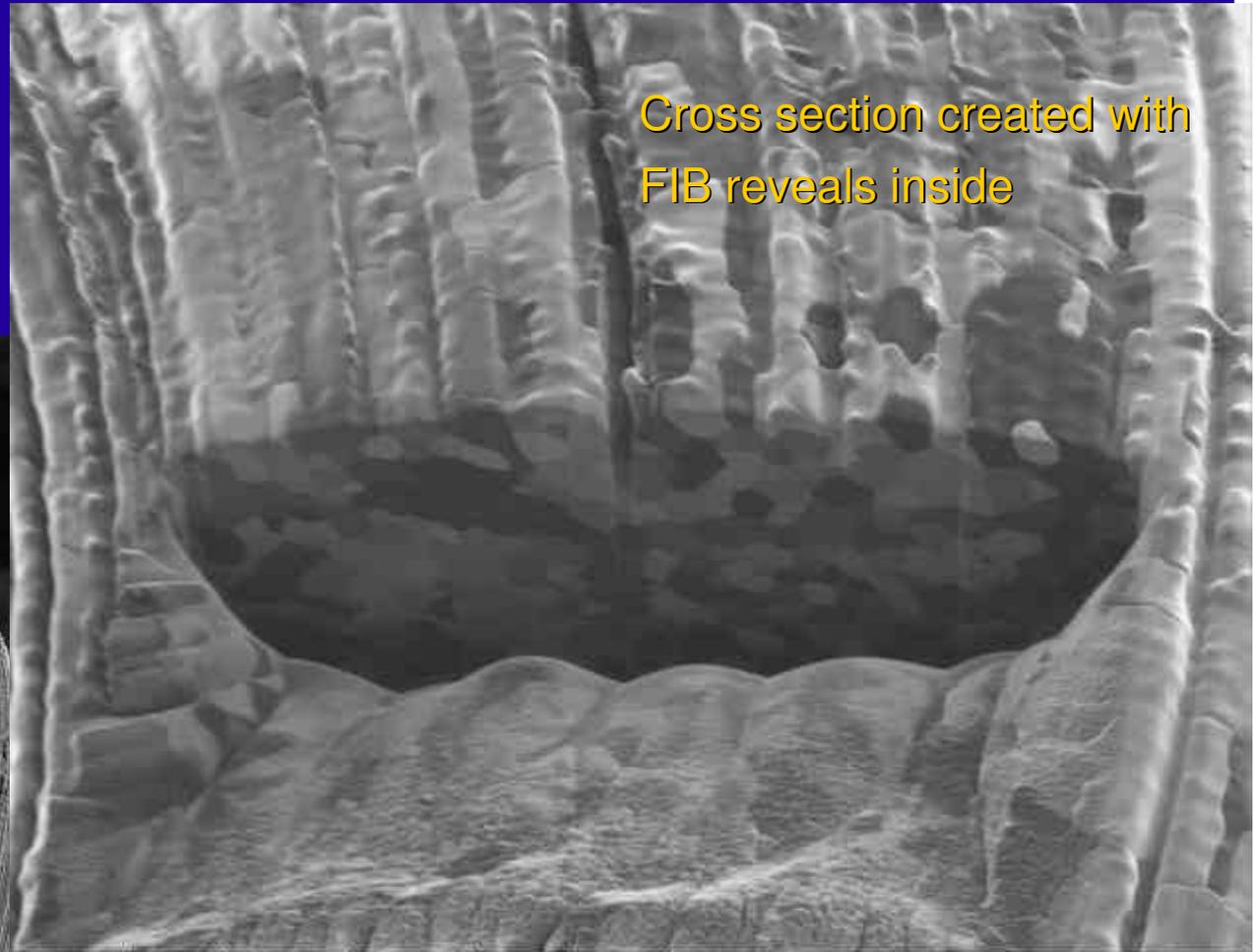
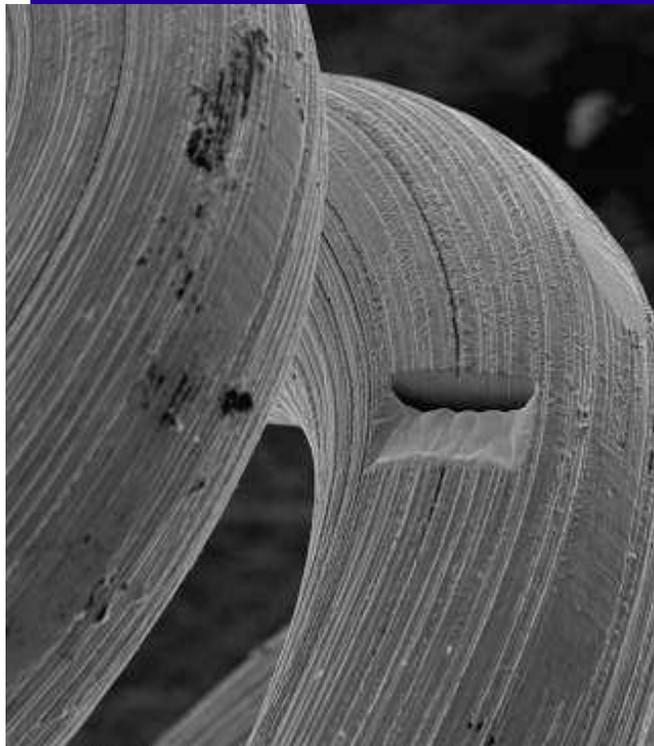
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FIB cut -> 3D imaging

Helix W wire for light bulb

Cross section created with FIB reveals inside



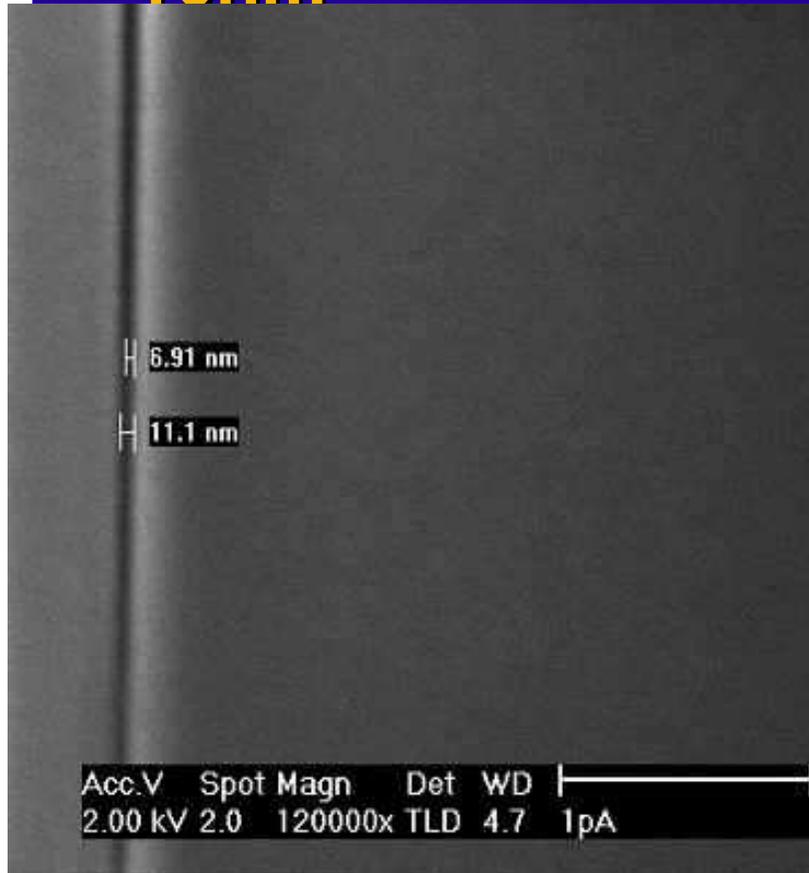
I-Beam	pA	Mag	Det	FWD	Tilt		50 µm
30.0 kV	50.0	1.20 kX	CDM-E	18.0	20.0°		

E-Beam	Spot	Mag	Det	FWD	Tilt		20 µm
5.00 kV	3	2.50 kX	CDM-E	5.345	25.6°		

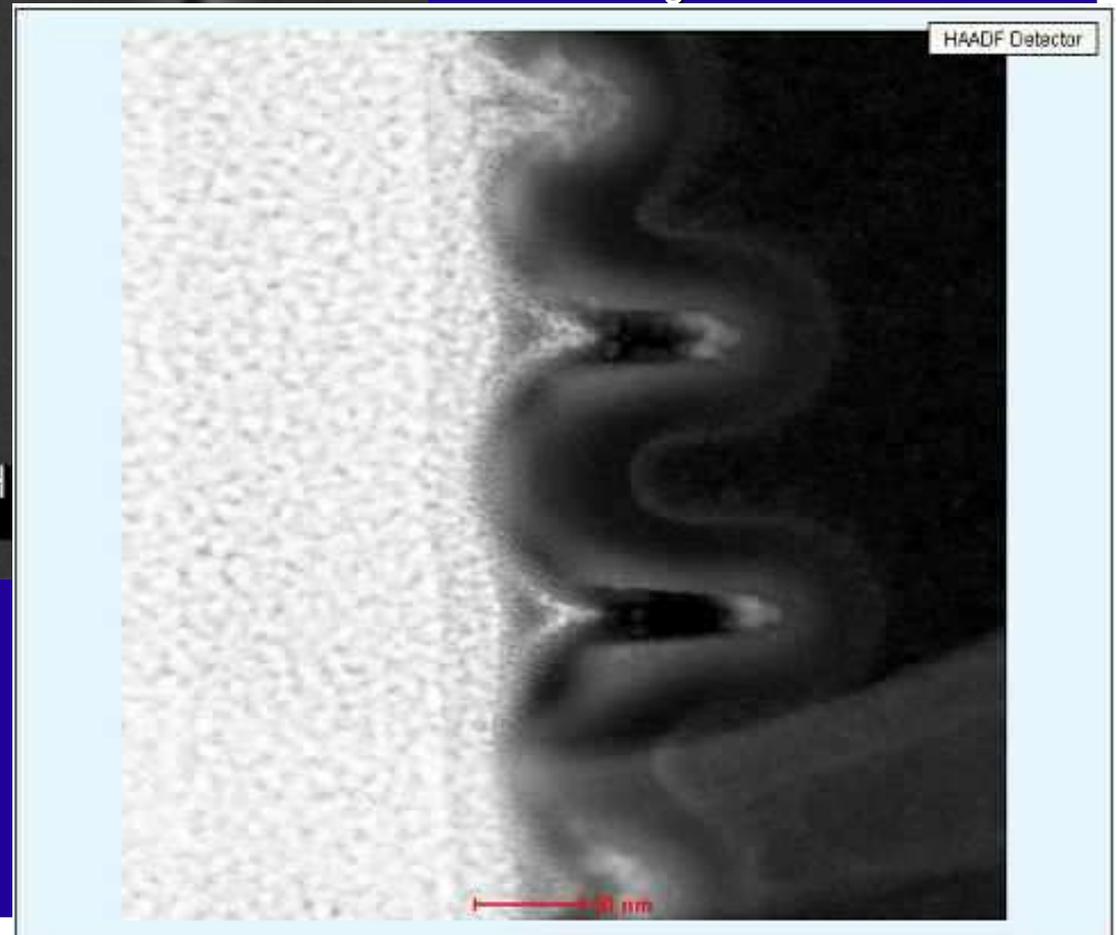


Nano-machining Channel Width ~10nm

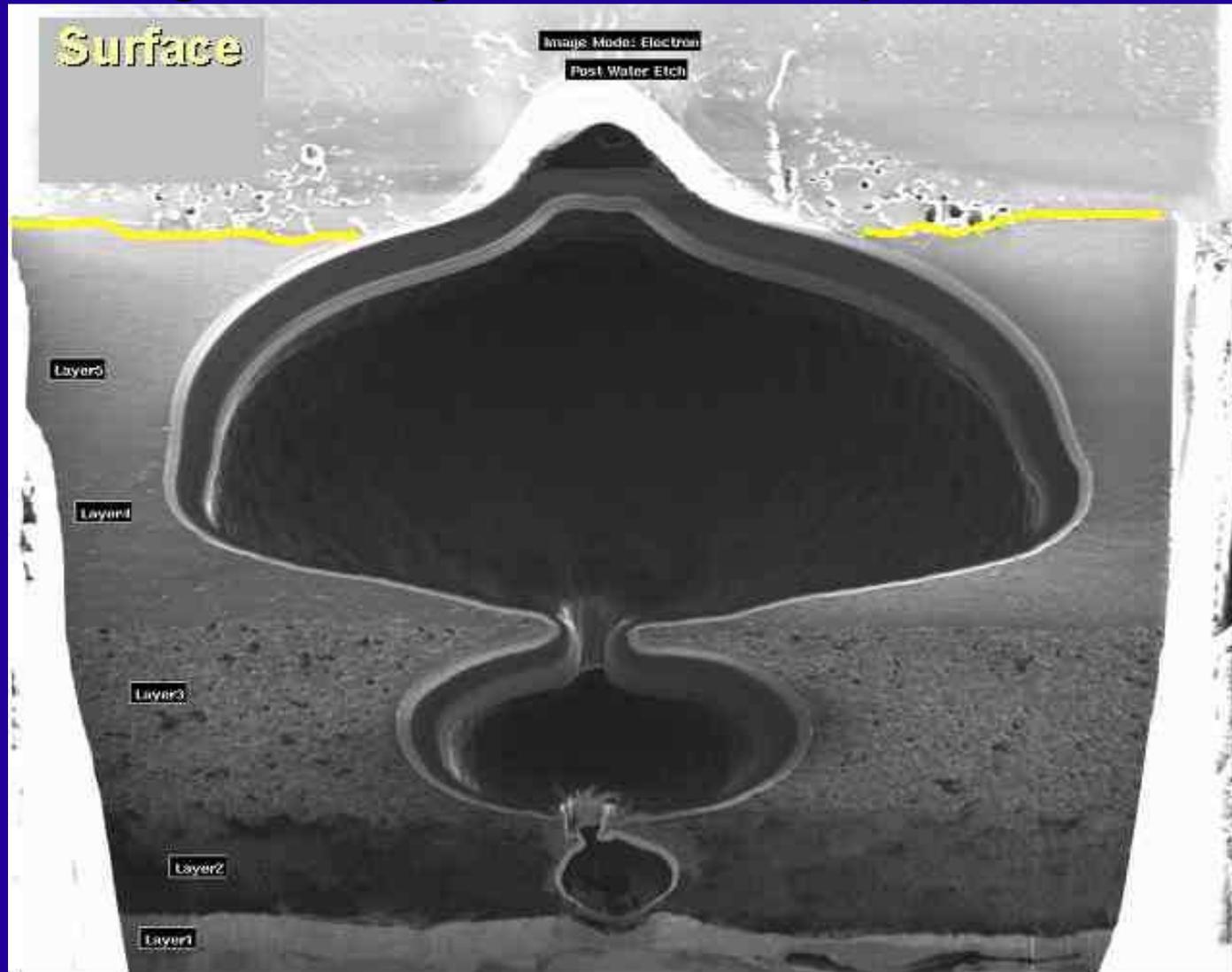
▶ TEM image of cross section



- SEM image of lines milled with 1pA Ga⁺ ion beam

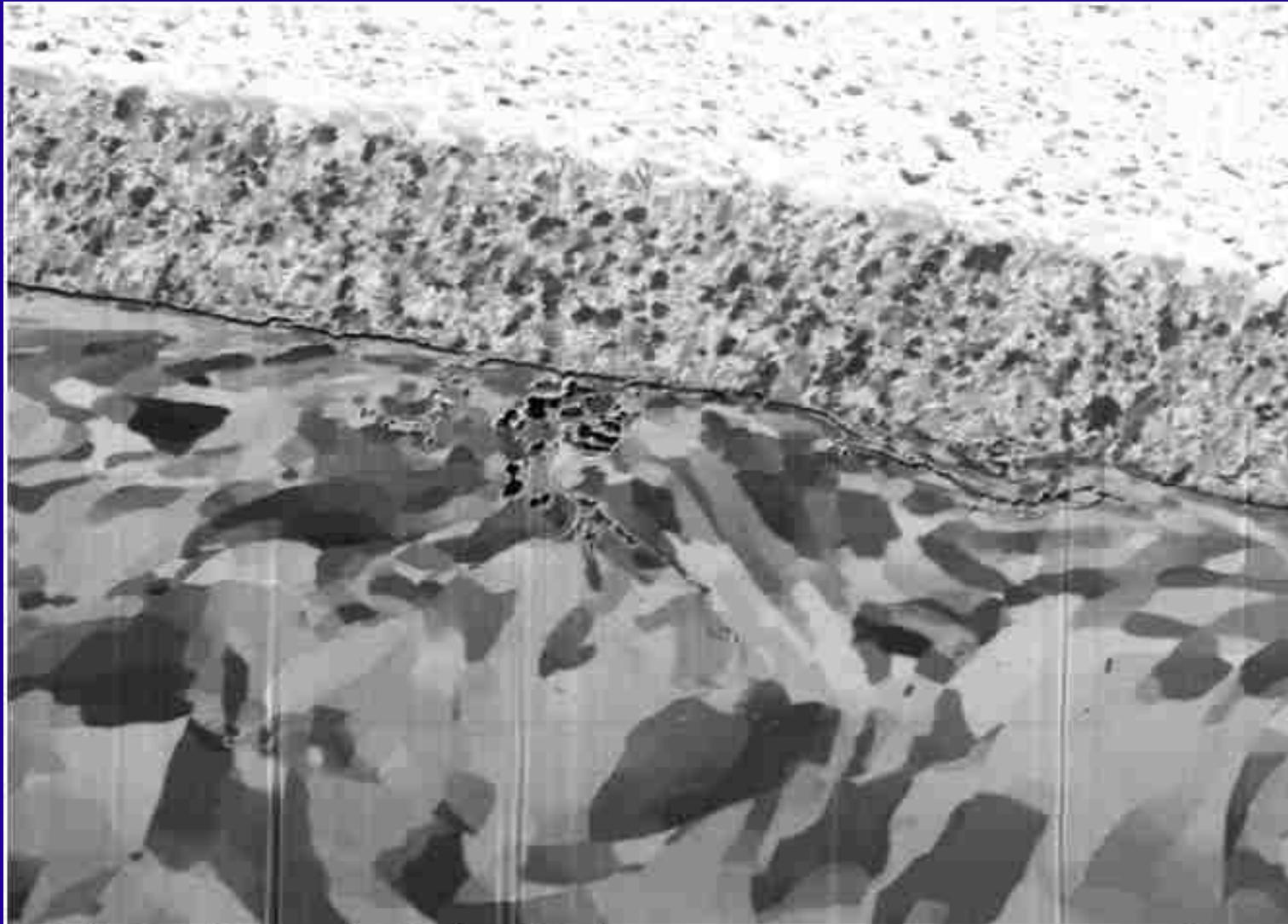


Micro Engineering ~1.4 million μm^3 Removed



Auto paint film defect **Field of View 140 microns**
Courtesy MPA

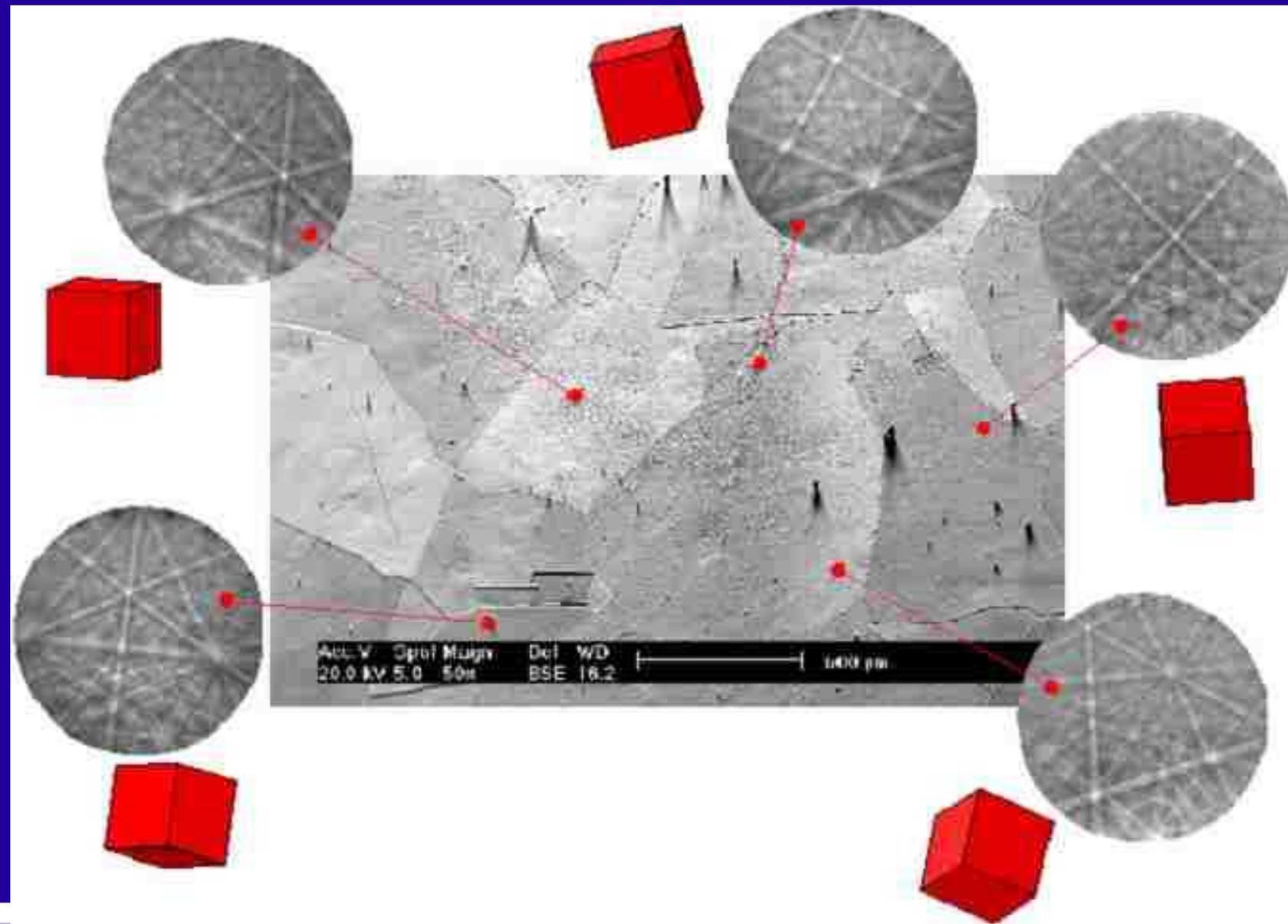
Channeling image contrast



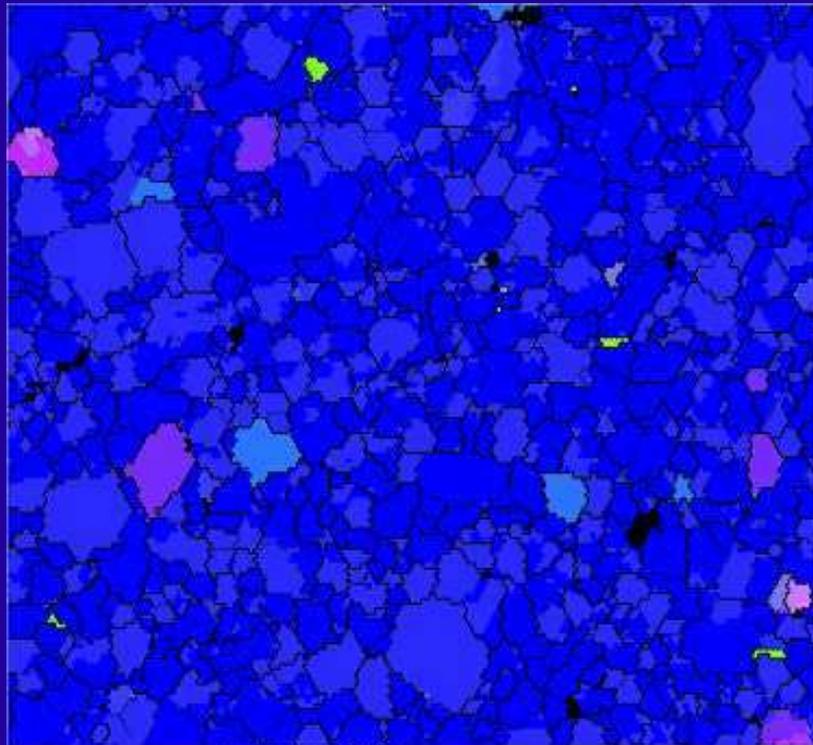
pA 10.0	Det SED	Mag 25.0 KX	Tilt 45.0°	HFW 12.2 μm	5 μm
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FEI™

Quantitative micro crystallography - OIM

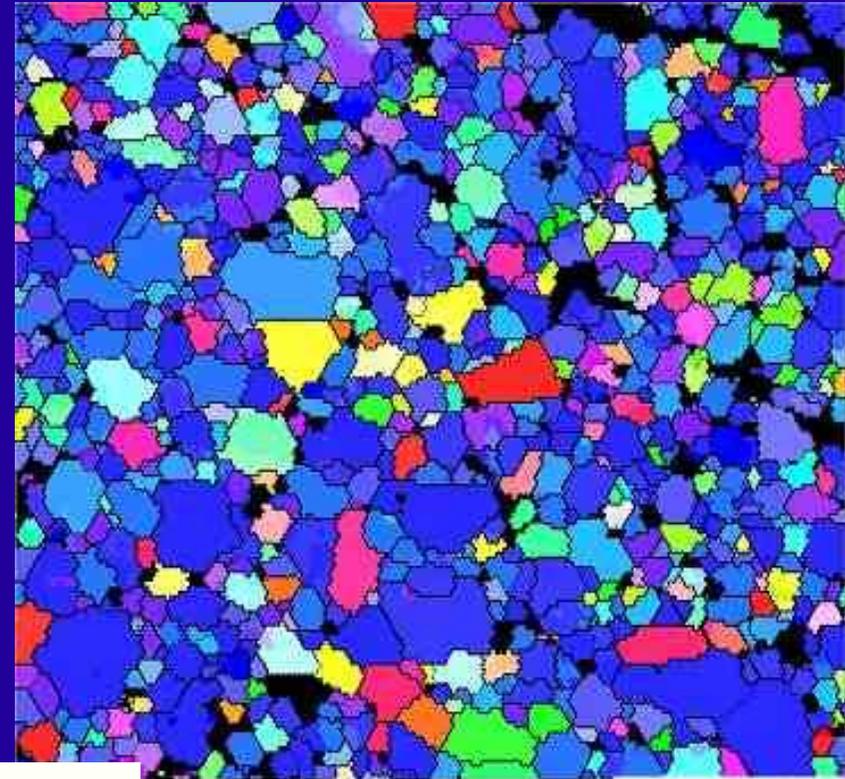


Semi-conductor: Al film for SC



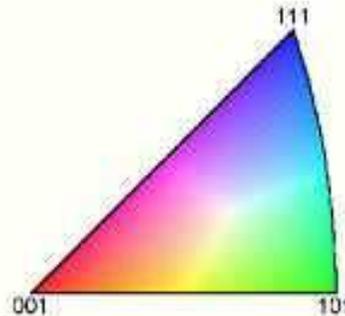
7.00 μm - 35 steps
boundary levels: 5.0° 15.0°
Tiled [001] IPF Map

High Mean Time to Failure

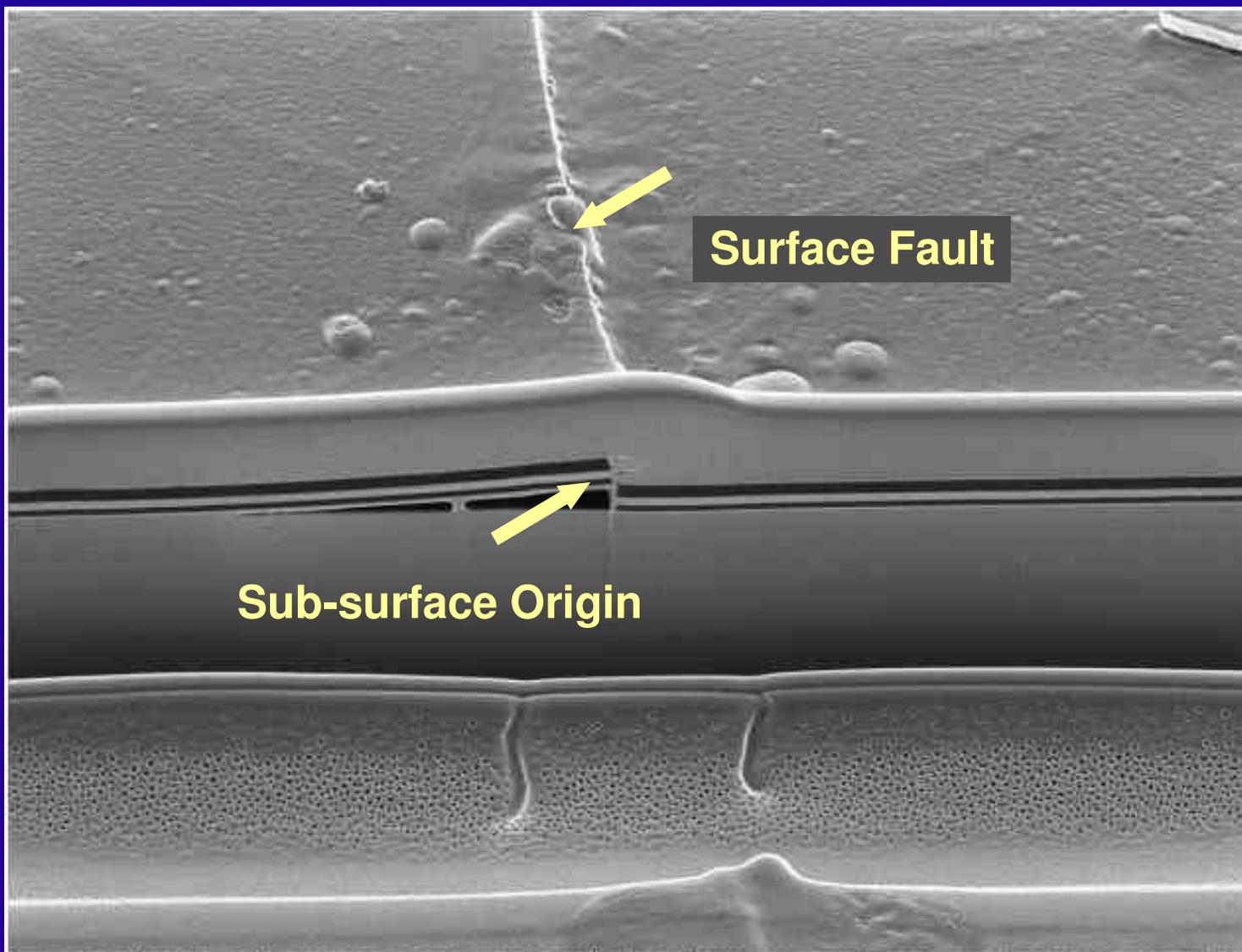


boundary levels: 5.0° 15.0°
Tiled [001] IPF Map

Low Mean Time to Failure



Expose 3rd dimension



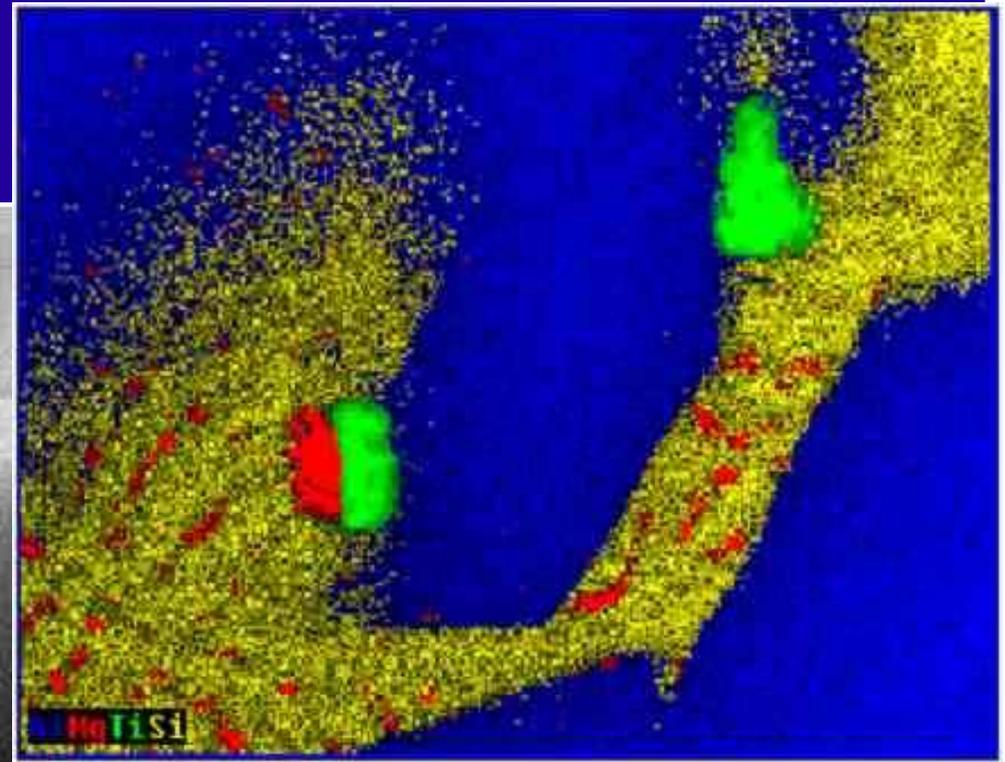
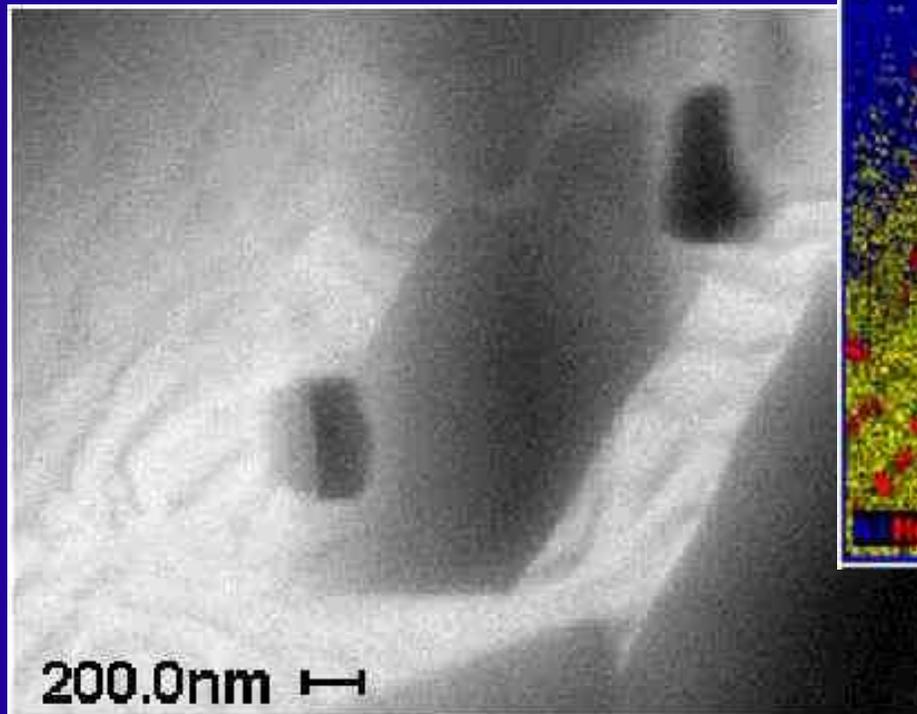
Surface Fault

Sub-surface Origin

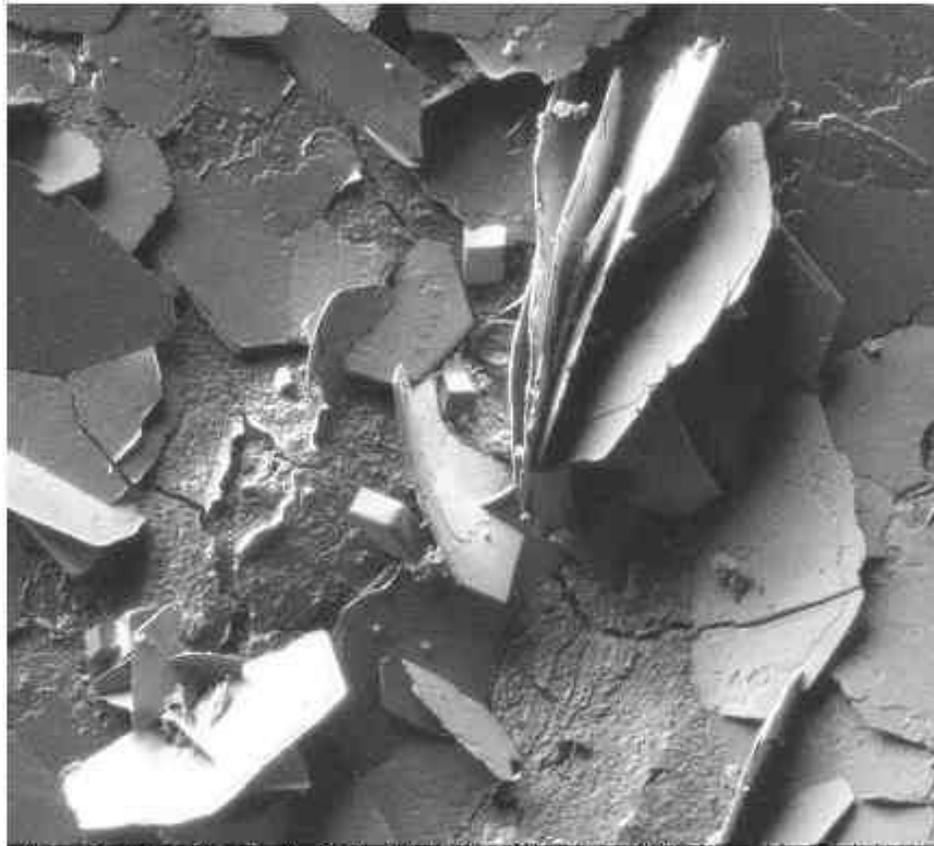
Beam	Mag	Tilt	pA	HFW	SRot	10/13/00	2 μm
30.0 kV	15.0 kX	45.0°	8.00	20.3 μm	0.0°	11:10:53	

Foil preparation - STEM

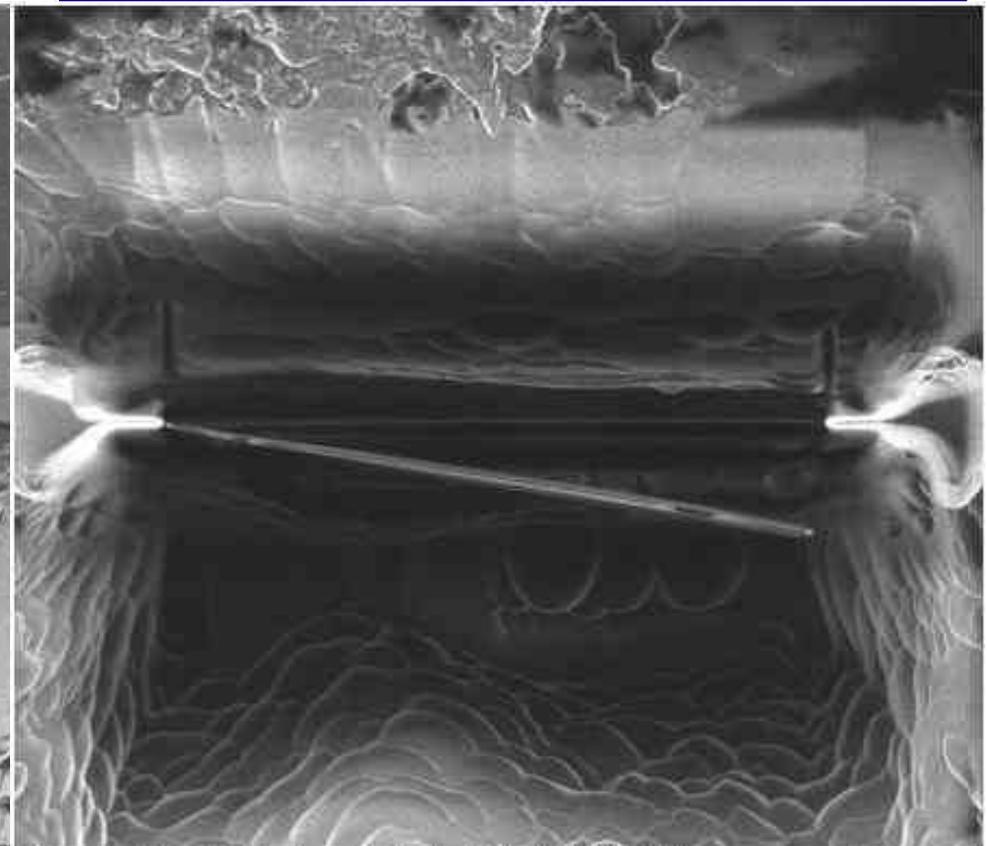
- ◆ Sub-nm resolution SEM
- ◆ Dark-field imaging in DualBeam
- ◆ UHR elemental mapping



Foil preparation - TEM

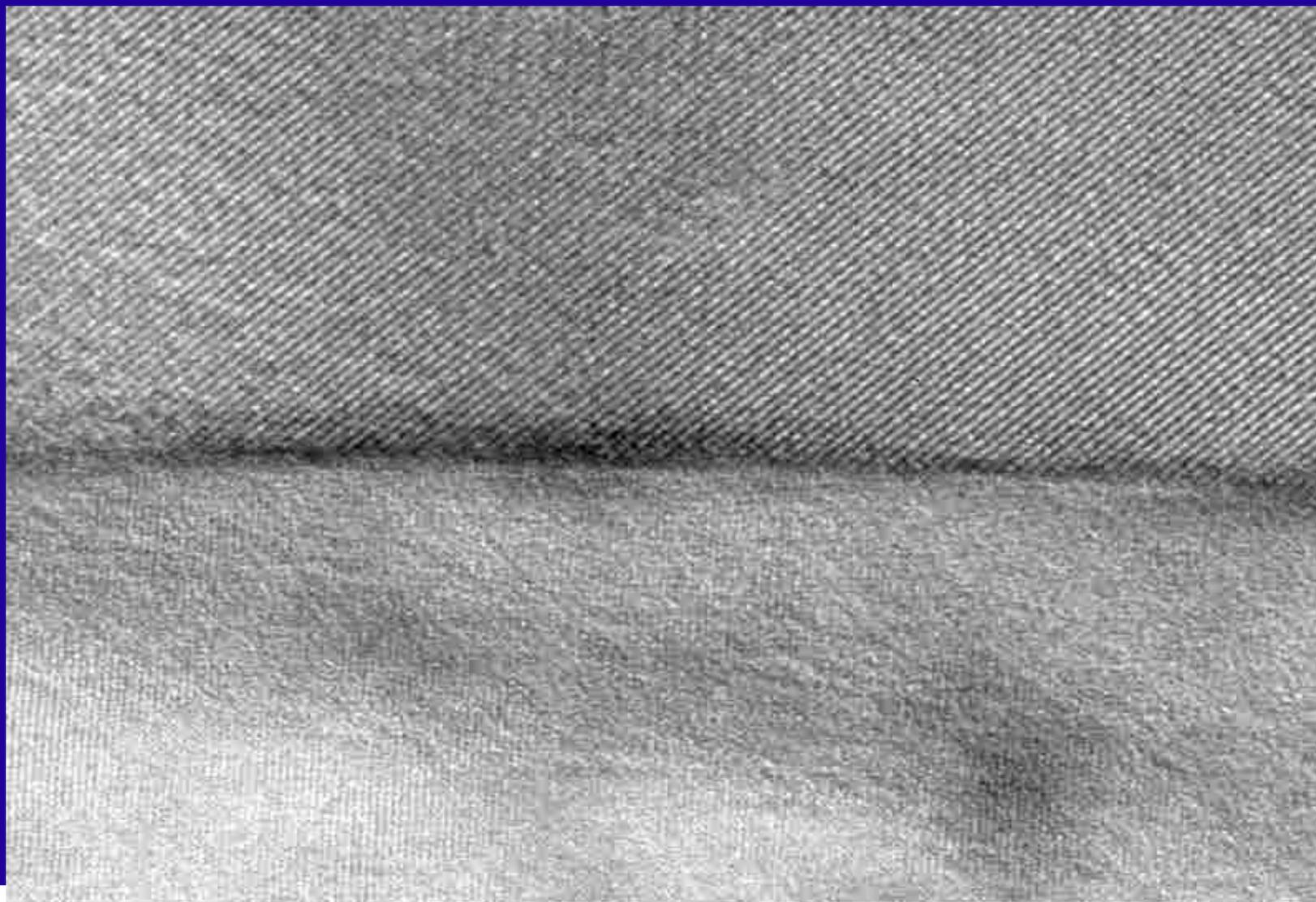


Beam	Mag	Tilt	pA	HFW	SRot	10/11/00	5 μ m
30.0 kV	6.50 kX	20.0°	95.0	46.8 μ m	0.0°	13:37:24	



Beam	Mag	Tilt	pA	HFW	SRot	10/11/00	2 μ m
30.0 kV	15.0 kX	1.0°	95.0	20.3 μ m	0.3°	16:42:33	

HR TEM image

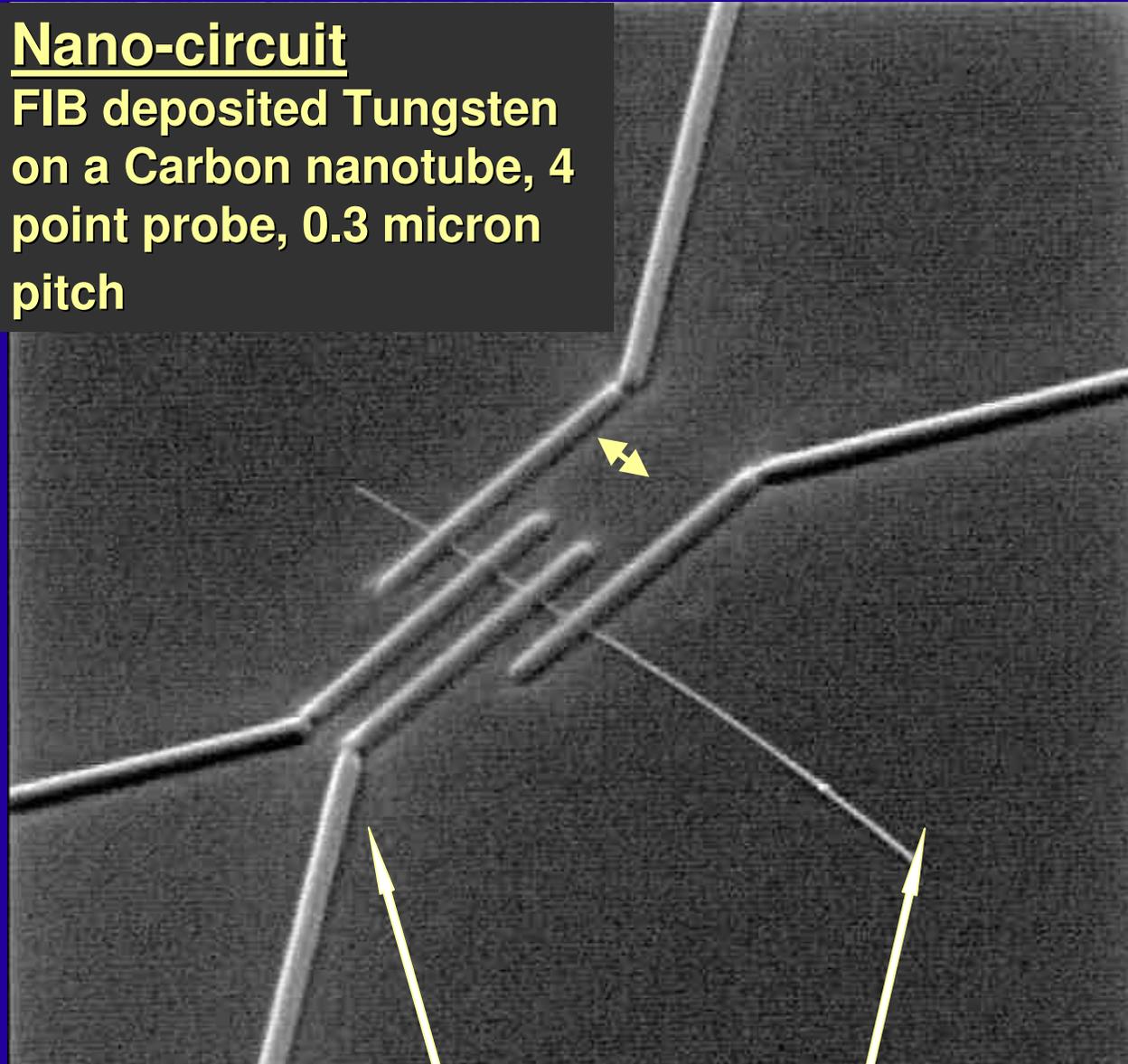


Deposition

- Nanotube probing

Nano-circuit

FIB deposited Tungsten on a Carbon nanotube, 4 point probe, 0.3 micron pitch



Deposited Tungsten

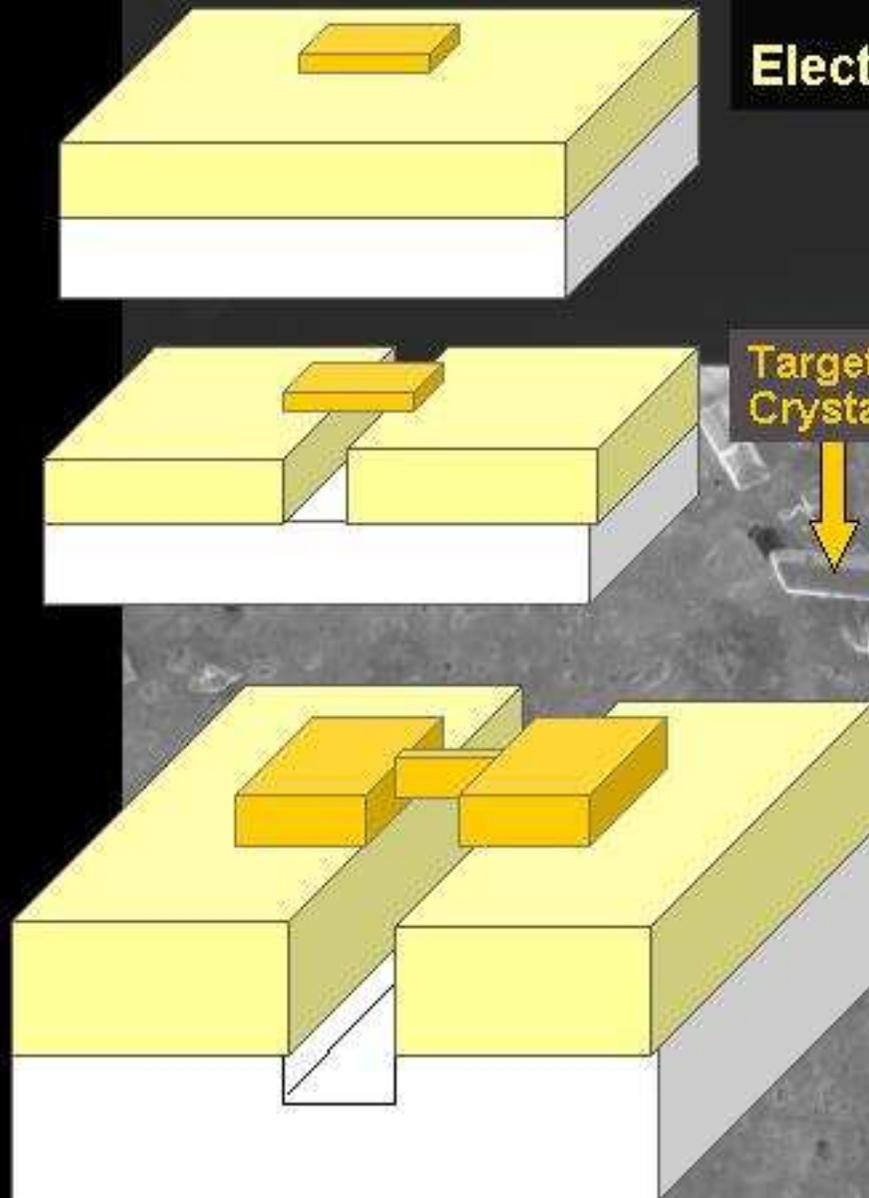
Carbon nano-tube

Combined benefits DualBeam - example

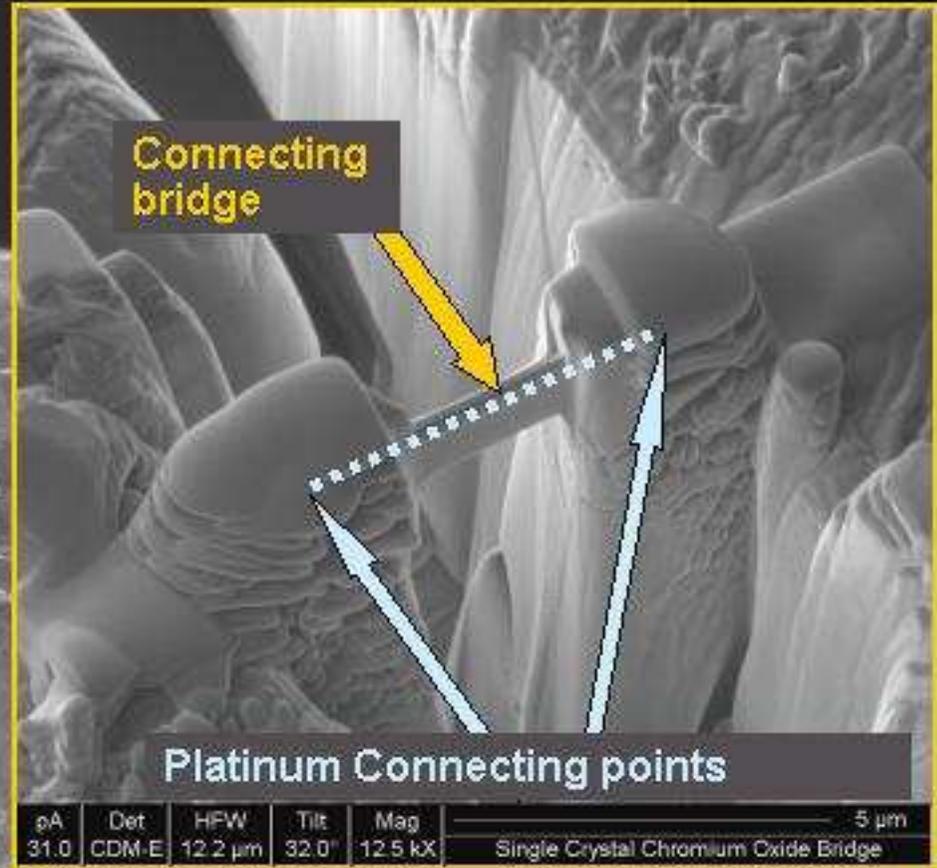
- How to measure electrical properties of a 5 μm Chromium Oxide single crystal on a conductive substrate?
- The DualBeam as a multipurpose Nano-scale experimental workstation
 - » Imaging
 - » Milling
 - » Depositing
 - » Measuring



Single crystal measurements: Electrical properties of Chromium oxide



Target
Crystal



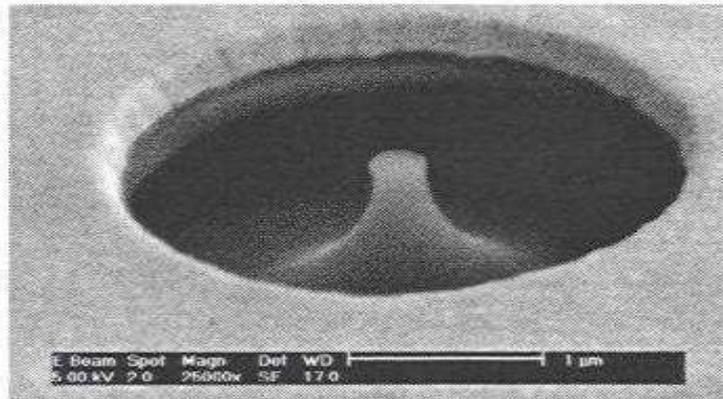
Chromium Oxide Particle
Conducting Substrate
Insulating Substrate

Courtesy of S.Liou,
U.Nebraska

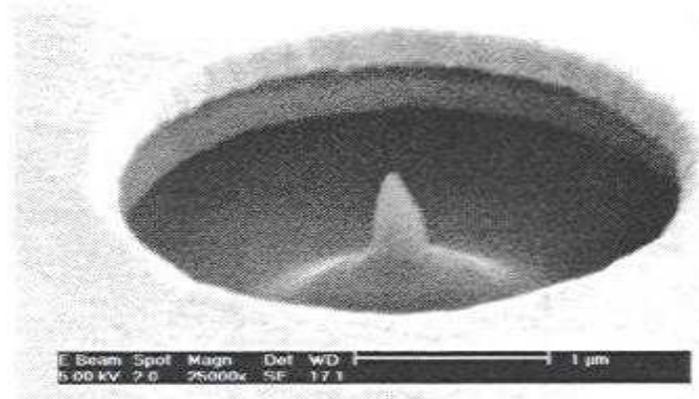
20 μ m
Single Crystal Chromium Oxide Bridge Target

Attempt to sharpen Field emitter array with FIB (Osaka University)

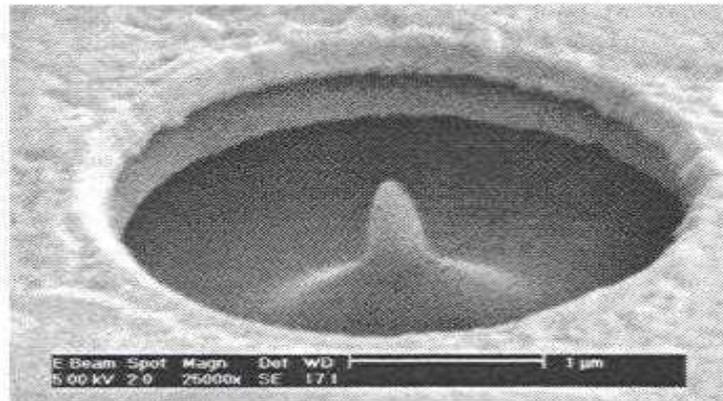
Si FEA after FIB Sharpening



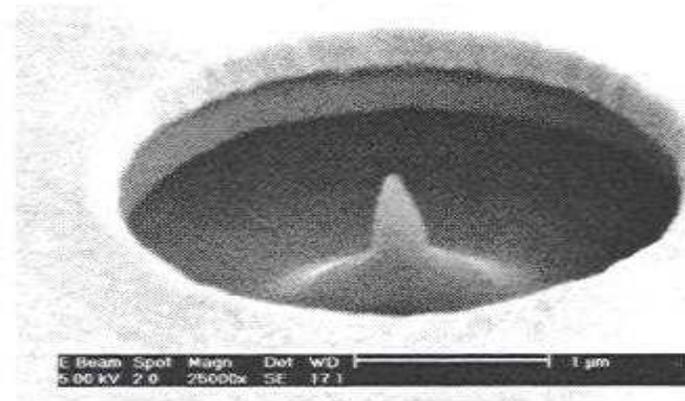
$t = 0$ s



$t = 10$ s



$t = 5$ s



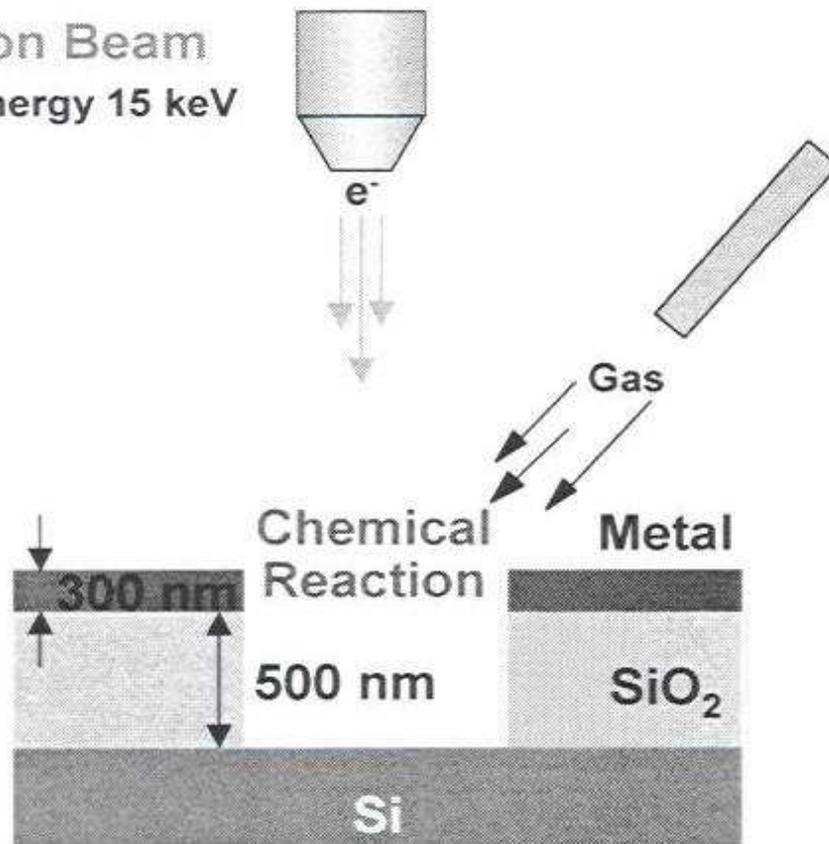
$t = 15$ s

$i = 7$ pA

Nano technology: new EDIB

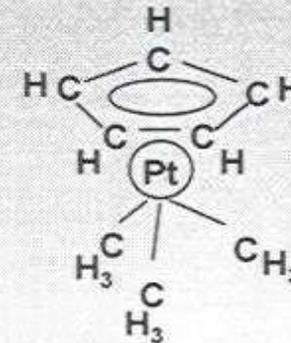
Pt Deposition

Electron Beam
Beam energy 15 keV



Gas Injection System

Gas : $C_5H_5Pt(CH_3)_3$



gas flow

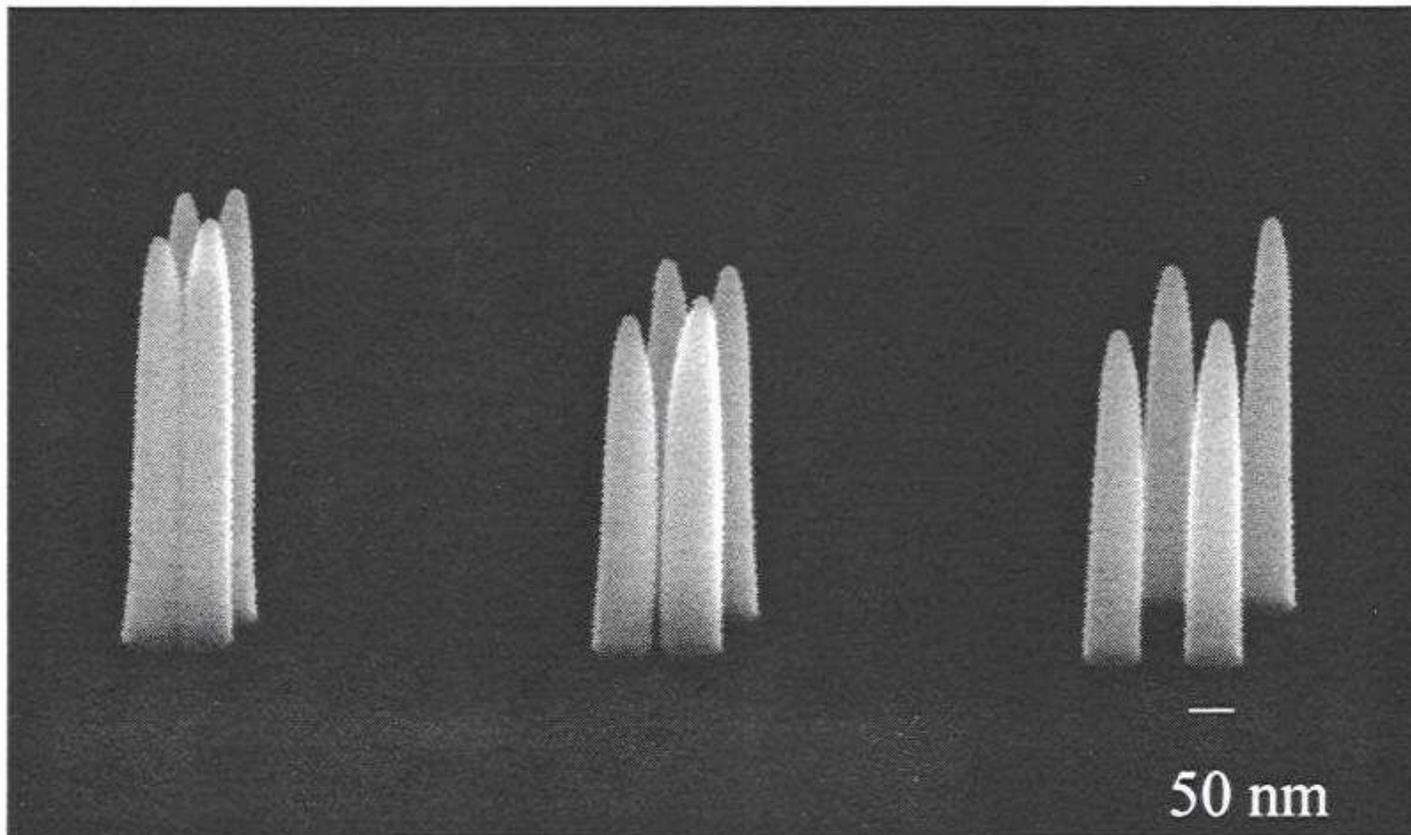
$10^{18} \sim 10^{19}$ molecule / $cm^2 \cdot s$

vapor pressure : 53 mTorr

melting point : 30~31 °C

Nano technology: new EDIB

Pt Pillars by E-Beam Induced Deposition



DualBeam: best of both worlds

- FIB for machining - milling deposition
 - » Use a little for imaging
- SEM for imaging, analysis and measuring
 - » Used a little for machining - deposition
- Applications in nano technology, polymers, metals, life-science, pharmaceuticals.